12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20260807002.1	PCN Issued	August 07, 2026
Qualification of additional BOM materials for select devices		Sample request deadline:	October 06, 2026
		Estimated 1st ship date:	November 05, 2026
***Sample requests received after** October 06, 2026* **will not be supported.**			

Change type(s)
Assembly Process Assembly Material

PCN Details

Description of Change:

This PCN is to inform of the qualification of additional BOM options for the devices in the product affected section as follows. Devices will remain at current Assembly sites.

	Current	Additional
Wire diam/type	0.96mil Au	0.8mil Cu
Mount Compound	4073495	4211470
Mold Compound	4205442	4222198

Qual details are provided in the Qual Data Section.

Reason for Change:	Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability:	Request the Supporting Data Packet (SDP) for more details on the changes.
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:	None

Products Affected:

SE2403APAGA	TMS320LF2403APAG4	TMS320LF2406APZAR
SE320LF2406APZA	TMS320LF2403APAGS	TMS320LF2406APZS
TMS320LF2401AVFA	TMS320LF2406APZA	TMS320LF2406APZSG4
TMS320LF2401AVFAR	DHDLF2406APZA	TMS320LF2407APGEA

TMS320LF2401AVFS	LF2406APZA-GREE	TMS320LF2407APGEG4
TMS320LF2403APAGA	TMS320LF2406APZAG4	TMS320LF2407APGES

Qualification Report

Approve Date 12-MAY -2026

NOTE: Extension to TI factory change announced in PCN 20180219000

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TMS320LF2407APGEA
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0

QBS: Qual By Similarity, also known as Generic Data
Qual Device TMS320LF2407APGEA is qualified at MSL3 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2509-051

APPENDIX: ORIGINAL FACTORY QUALIFICATION

Qualification Report

UniBOM Qualification for QFP packages in TITL
Approve Date 21-Dec-2017

Product Attributes

Attributes	Qual Device: ADS1675IPAG	Qual Device: MSP430FR6989IPZR	Qual Device: TL16C554AIPNR	Qual Device: TPS2383APMR
Assembly Site	TAI	TAI	TAI	TAI
Package Family	TQFP	LQFP	LQFP	LQFP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	DP1DM5	DMOS6	DL-LIN	DL-LIN
Wafer Process	50HPA07	HPE035	C21	LBC4

- Qual Device ADS1675IPAG_ is qualified at LEVEL4-260C
- Qual Devices qualified at LEVEL3-260C: TPS2383APMR, TL16C554AIPNR, MSP430FR6989IPZR

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: ADS1675IPAG	Qual Device: MSP430FR6989IPZR	Qual Device: TL16C554AIPNR	Qual Device: TPS2383APMR
AC	Autoclave, 121C	96 Hours	3/231/0	3/231/0	3/231/0	3/231/0
HAST	Biased HAST, 130C, Vddmax	96 Hours	-	3/231/0	-	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0	3/231/0	3/231/0	3/231/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass	Pass
MSL	Moisture Sensitivity	Level 3-260C	-	3/36/0	3/36/0	3/36/0
MSL	Moisture Sensitivity	Level 4-260C	3/36/0	-	-	-
TC	Temperature Cycle, -6C/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0
VM	Post Autoclave Visual Quality Reliability Inspection	--	-	-	3/6/0	3/6/0
VM	Post HAST/THB Visual Quality Reliability Inspection	--	-	1/2/0	-	-
VM	Post Temp. Cycle Visual Quality Reliability Inspection	--	-	-	3/6/0	3/6/0
YLD	FTY and Bin Summary	--	Pass	Pass	Pass	Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable.
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1000 Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours.
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1000 Hours, and 170C/420 Hours.
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles.

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your

application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.